Taiwan Semiconductor

1A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- Low power loss, high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

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- Freewheeling
- Snubber
- DC/DC converters
- Automotive application

MECHANICAL DATA

• Case: SOD-128

Molding compound meets UL 94V-0 flammability rating

• Terminal: Matte tin plated leads, solderable per J-STD-002

• Meet JESD 201 class 2 whisker test

Polarity: Indicated by cathode band

• Weight: 0.027g (approximately)

KEY PARAMETERS						
PARAMETER	VALUE	UNIT				
I _F	1	Α				
V _{RRM}	200 - 1000	V				
I _{FSM}	30	Α				
T _J MAX	175	°C				
Package	SOD-128					
Configuration	Single die					









SOD-128



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)							
PARAMETER	SYMBOL	RS1D FSH	RS1G FSH	RS1J FSH	RS1K FSH	RS1M FSH	UNIT
Marking code on the device		RS1DFS	RS1GFS	RS1JFS	RS1KFS	RS1MFS	
Repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value	V _{R(RMS)}	140	280	420	560	700	V
Forward current	l _F	1					Α
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load	IFSM	30					А
Junction temperature	ΤJ	-55 to +175					°C
Storage temperature	T _{STG}	-55 to +175					°C

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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance	R _{OJL}	29	°C/W			
Junction-to-ambient thermal resistance	Reja	84	°C/W			
Junction-to-case thermal resistance	Rejc	30	°C/W			

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I _F = 0.5A, T _J = 25°C		0.94	1.10	V
Comment valtage (1)		I _F = 1.0A, T _J = 25°C	.,	1.01	1.30	V
Forward voltage ⁽¹⁾		I _F = 0.5A, T _J = 125°C	V _F	0.79	1.00	V
		I _F = 1.0A, T _J = 125°C		0.88	1.20	V
Davaraa aurrant @ ratad \	ı_ (2)	T _J = 25°C	1_	-	5	μA
Reverse current @ rated \	'R\ ² /	T _J = 125°C	I _R	-	50	μA
Junction capacitance		1MHz, V _R = 4.0V	Сл	7	-	pF
	RS1DFSH RS1GFSH		t _{rr}	-	150	ns
Reverse recovery time	RS1JFSH	$I_F = 0.5A, I_R = 1.0A$ $I_{II} = 0.25A$		-	250	ns
	RS1KFSH RS1MFSH	III = 0.23A		-	500	ns

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION						
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING				
RS1xFSH	SOD-128	14,000 / Tape & Reel				

Notes:

1. "x" defines voltage from 200V(RS1DFSH) to 1000V(RS1MFSH)



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

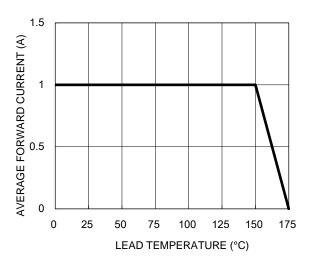


Fig.3 Typical Reverse Characteristics

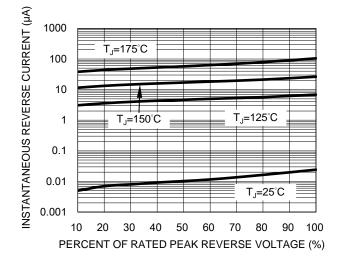


Fig.2 Typical Junction Capacitance

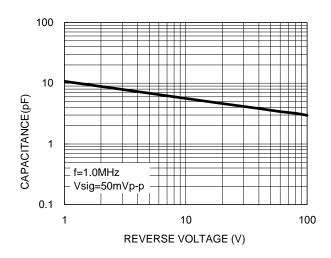
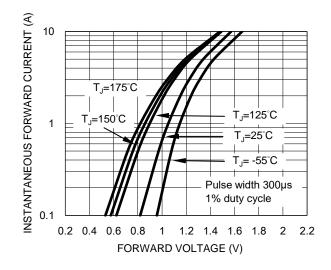


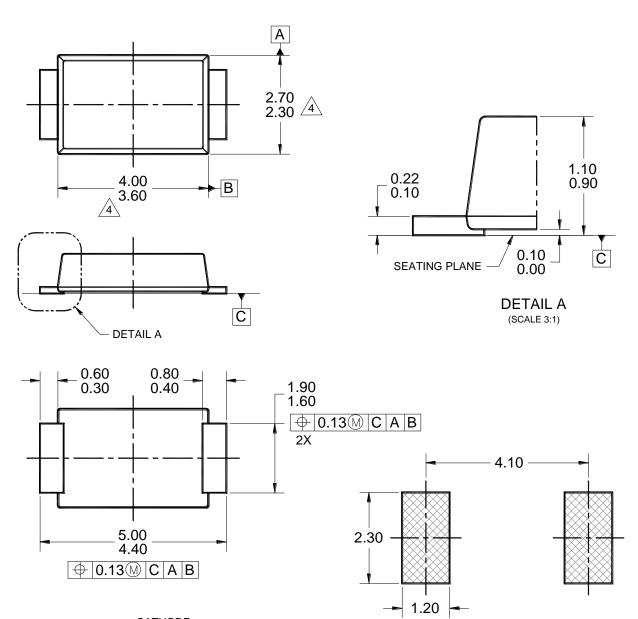
Fig.4 Typical Forward Characteristics

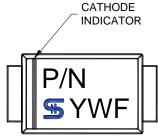




PACKAGE OUTLINE DIMENSIONS

SOD-128





MARKING DIAGRAM

P/N = MARKING CODE YW = DATE CODE

F = FACTORY CODE

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.

SUGGESTED PAD LAYOUT

- 3. PACKAGE OUTLINE REFERENCE: JEDEC DO-221, VARIATION AD, ISSUE B.
- MODED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
- 5. DWG NO. REF: HQ2SD07-SOD128-039 REV A.

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